PRODUCT CHANGE NOTICE

Alternate Manufacturing Site for Assembly of Intersil Product ISL1536*

Refer to: PCN11023

Date: March 1, 2011

March 1, 2011

To: Our Valued Intersil Customer

Subject: Alternate Manufacturing Site for Assembly of Intersil Product ISL1536* – STATS ChipPAC Malaysia

This notice is to inform you that Intersil will begin using the STATS ChipPAC Malaysia (SCM) facility as alternate site for assembly of the listed ISL1536* products. This action will expand current capabilities and capacities to optimize Intersil's ability to meet customer's delivery requirements. The product and site-specific qualification activities are complete.

Products affected: ISL1536IRZ ISL1536IRZ-T13

The STATS ChipPAC Malaysia (SCM) facility is ISO 9001:2008 and ISO/TS 16949:2009 certified and currently qualified as a supplier to Intersil for assembly of QFN packaged products. There will be no change in the package outline drawing (POD) or the moisture sensitivity level (MSL). The qualified material set combinations are as follows:

Material	Current	SCM	
Mold Compound	Sumitomo EME-G770HCD	Sumitomo EME-G770	
Die Attach	Ablebond 8290	Ablebond 8290	
Bond Wire	1.0 mil Gold (Au)	1.0 mil Gold (Au)	
Lead Frame	C194	C194	

The assembly qualification plan is designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function, or interchangeability of the product. A summary of the qualification results is included. The remainder of the manufacturing operations (wafer fabrication, package level electrical testing, shipment, etc.) will continue to be processed to previously established conditions and systems.

Product affected by this change is identifiable via Intersil's internal traceability system. In addition, product assembled at SCM may also be identified by the assembly site code (country of assembly) when marked on the devices. The assembly site code for the SCM facility is "H".

Intersil will take all necessary actions to conform to agreed upon customer requirements and to ensure the continued high quality and reliability of Intersil products being supplied. Customers may expect to receive product assembled at either the current or the newly qualified sites beginning *ninety* days from the date of this notification or earlier with approval.

If you have concerns with this change notice, Intersil must hear from you promptly. Please contact the nearest Intersil Sales Office or call the Intersil Corporate line at 1-888-468-3774, in the United States, or 1-321-724-7143 outside of the United States.

Regards,

Intersil Corporation

PCN11023

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PCN11023 – Reliability Summary

Stress / Conditions	Duration	Sample Size	Results
High Temp Storage $Ta = 150C$	1000 Hours	0/78	Passed
Acc. Bond Integrity (ABI) / Wire Pull $Ta = 175C$	96 Hours	0/15	Passed
Moisture Sensitivity Classification	MSL 3	0/66	Passed
ubHAST 130C / 85% RH	96 Hours	0/78	Passed
Temp Cycle MIL +150C / -65C	500 Cycles	0/78	Passed
Destructive wire pull after Temp Cycle MIL +150C / -65C	500 Cycles	0/6	Passed

